PCN Number:	201701100	20170110001 PCN Date: Jan. 12, 2		12, 201	17			
Title: Datasheet fo	r ADS8363, ADS7263, ADS7223							
Customer Contact:	PCN Manager				Dept:		Quality Services	
Change Type:					-			,
Assembly Site			Design				Wafer	Bump Site
Assembly Process		d						Bump Material
Assembly Materia		Ħ	Part number change			\Box	Wafer Bump Process	
Mechanical Specif		Ħ	Test Site			П	Wafer Fab Site	
Packing/Shipping/			Test Proce	ess			Wafer	Fab Materials
							Wafer	Fab Process
Notification Details								
Description of Chang								
Texas Instruments Inc The product datasheet The following change h	(s) is being u _l	pda	ted as sun	nmarized belov				
Instruments				CDACE.	220			ADS7263, ADS7223
Changes from Revision B (January 2011) to F	Revis	sion C	SBASS	23C	-0010	DBER 2010-	-REVISED JANUARY 2017 Page
Added Device Information table, ESD Ratings table, Recommended Operating Conditions table, Feature Description section, Device Functional Modes section, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section 1 Changed ADS8363/7263/7223 to ADS8363, ADS7263, and ADS7223 throughout document 1 Changed Description section: changed last sentence of first paragraph and last paragraph 1 Changed Device Comparison Table title 2 Changed Pin Configuration and Functions section title 3 Changed footnote of Figure 1 and for clarity 4 Changed second and third columns of Midscale – 1 LSB row in Output Data Format table: changed –V _{REF} to –2V _{REF} in column 2, changed last two voltage values in column 3 5 Changed footnote of Figure 31 6 Changed footnote of Figure 32 7 Changed footnote of Figure 33 8 Changed footnote of Figure 34 8 Changed footnote of Figure 35 8 Changed footnote of Figure 36 8 Changed footnote of Figure 38 8 Changed footnote of Figure 30 8 Changed footnote of Figure 31 8 Changed footnote of Figure 36 8 Changed footnote of Figure 40 8 Changed footnote of Figure 40 8 Changed IFFh to 3FFh in bits 9-0 description of REFDAC1 Control Register and REFDAC2 Control Register								
The datasheet number	will be chang	iina	1					
Device Family						Change To:		
ADS8363, ADS7263,	ADS7223		SBAS523					SBAS523C
These changes may be http://www.ti.com/pro Reason for Change: To accurately reflect de	duct/ADS836 evice thermal	3 cha	aracteristic	es.				
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):								

No anticipated impact. This is a specification change announcement only. There are no changes

to the actual device.

Changes to product identification resulting from this PCN:						
None.						
Product Affected:						
ADS7223SRHBR	ADS7223SRHBT	ADS7263SRHBR	ADS7263SRHBT			
ADS8363SRHBR	ADS8363SRHBT					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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